

DISCLAIMER IN PATENT UNDER 37 CFR 1.321(a)

Name of patentee
TAYANAKA, Hiroshi

Docket Number (Optional)
09792909-3401

Patent Number
U.S. Patent No. 6,107,213

Date Patent Issued
August 22, 2000

Title of Invention
Method For Making Thin Film Semiconductor

I hereby disclaim the following complete claims in the above identified patent: Claim 20.

The undersigned is authorized to make this disclaimer on behalf of Sony Corporation, as indicated on the Power of Attorney of record.

The extent of my interest in said patent is (if assignee of record, state liber and page, or reel and frame, where assignment is recorded): Reel/Frame 008708/0321

The fee for this disclaimer is set forth in 37 CFR 1.20(d).

- ☐ Patentee claims small entity status. See 37 CFR 1.27.
- ☐ Small entity status has already been established in this case, and is still proper.
- ☐ A check in the amount of the fee is enclosed.
- ☒ Payment by credit card. Form PTO-2038 is attached.
- ☒ The Commissioner is hereby authorized to charge any fees which may be required or credit any overpayment to Deposit Account No. 19-3140. I have enclosed a duplicate copy of this sheet.

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Signed at Chicago, State of Illinois this 20th day of July, 2005.

Signature

David R. Metzger, Attorney of Record for Applicant Sony Corporation

Typed or printed name

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